

## CLAIMS

1. A composite ceramic substrate comprising;  
a ceramic substrate mounted with a surface-mounted component,  
an external terminal electrode connecting wiring pattern  
formed on the ceramic substrate and a surface electrode of a  
motherboard,  
a convex leg portion formed of resin such that an end face  
thereof supports the external terminal electrode, and  
a via-hole conductor formed in the leg portion and  
connecting the external terminal electrode and the wiring pattern.
2. The composite ceramic substrate according to claim 1,  
wherein the surface-mounted component is mounted on a first main  
face and/or a second main face of the ceramic substrate and the  
convex leg portion is disposed on the second main face of the  
ceramic substrate.
3. The composite ceramic substrate according to claim 2,  
wherein the convex leg portion is disposed at the periphery of  
the second main face of the ceramic substrate.
4. The composite ceramic substrate according to claim 3,  
wherein a plurality of the external terminal electrode is  
supported by the end face of a single convex leg portion.
5. The composite ceramic substrate according to claim 4, wherein  
the external terminal electrodes are not disposed at corners of  
the second main face of the ceramic substrate.
6. The composite ceramic substrate according to claim 5, wherein  
the corners are lower than the height where the external terminal

electrodes are disposed.

7. The composite ceramic substrate according to any one of claims 2 to 6, wherein the surface-mounted component is mounted between the convex leg portions on the second main face.

8. The composite ceramic substrate according to claim 7, wherein the surface-mounted component is supported with resin that is the same as that forming the convex leg portion.

9. The composite ceramic substrate according to claim 8, wherein a round portion is formed between the convex leg portion and the resin coating the surface-mounted component.

10. The composite ceramic substrate according to claim 8 or 9, wherein the surface of the resin coating the surface-mounted component has a slit.

11. The composite ceramic substrate according to any one of claims 1 to 10, wherein an edge of the convex leg portion is formed into a rounded shape.

12. The composite ceramic substrate according to any one of claims 1 to 11, wherein the via-hole conductor is formed with conductive resin having flexibility.

13. The composite ceramic substrate according to any one of claims 1 to 12, wherein the ceramic substrate is a multilayer ceramic substrate formed by laminating a plurality of low temperature co-fired ceramic layers.

14. The composite ceramic substrate according to any one of

claims 1 to 13, wherein the surface-mounted component has external terminal electrodes in an array.